Abstracts

High Density Microwave Packaging Program

E.D. Cohen. "High Density Microwave Packaging Program." 1995 MTT-S International Microwave Symposium Digest 95.1 (1995 Vol. I [MWSYM]): 169-172.

The objective of the High Density Microwave Packaging (HDMP) program is to develop and establish the producibility of complex shape, light weight, and high density microwave frequency transmit/receive (T/R) modules. The approach is to focus development on modules for active array radar applications, particularly for such platforms as the next-generation of F-22s, comparable Navy aircraft, and Army helicopters. A key technical requirement for successful fielding of active aperture phased arrays on aircraft and space-based platforms is to integrate all array elements, including radiating elements, microwave components, RF and DC interconnects, distribution channels, signal processing control elements, and thermal management systems into compact, minimum size packages that meet funtional and environmental requirements.

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